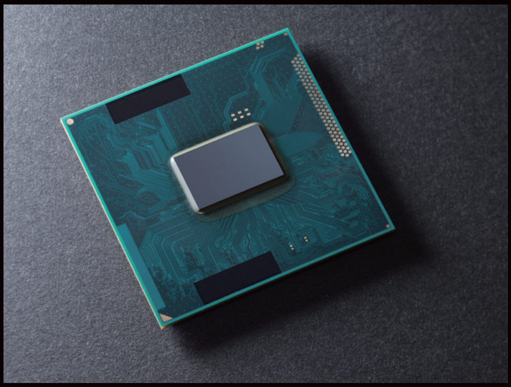
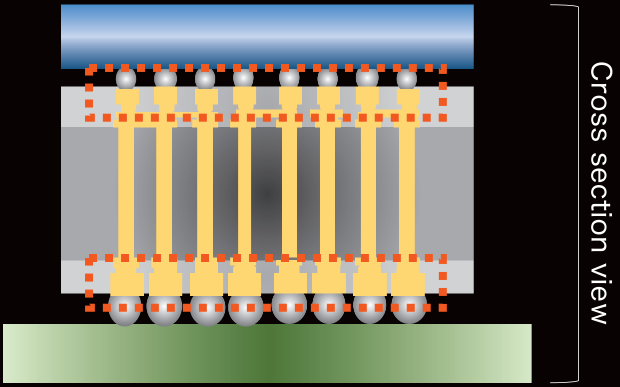
Acid copper plating additive to FO-PLP/WLP for copper pillar formation

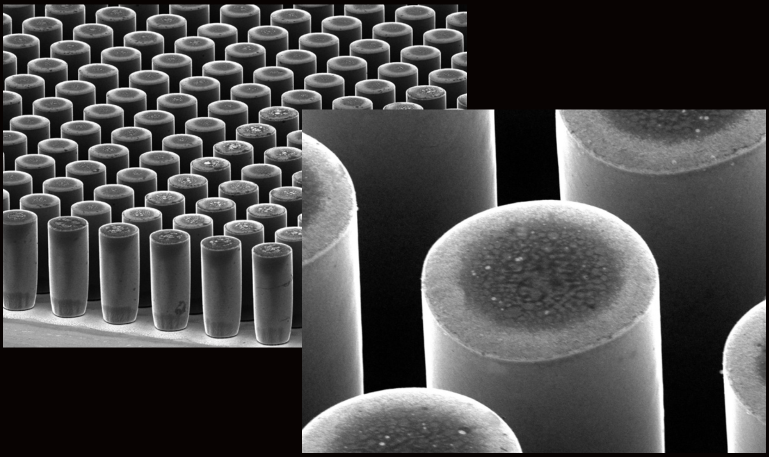
TORYZA LCN SP

- Can form Cu pillar with high thickness uniformity
- Can make small diameter pillar, can apply for narrow pitch
- Flat top and uniform shapes are obtained

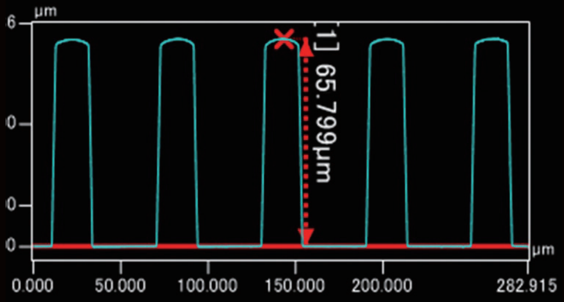




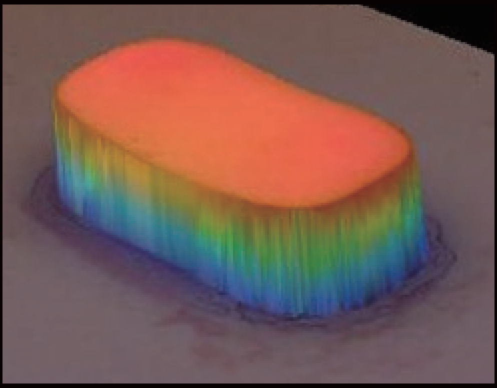
Flat top surface, high thickness uniformity



Current density: 8A/dm²
Pillar height: 65µm
Pillar diameter: 15µm
Pitch: 15µm



Flat surface formation



Current density: 5A/dm²
Pillar height: 30µm

Flat shape is obtained at the top to realize high connection reliability